

Revision History	
Revision	Notes

Designator
TPS544C20.SchDoc



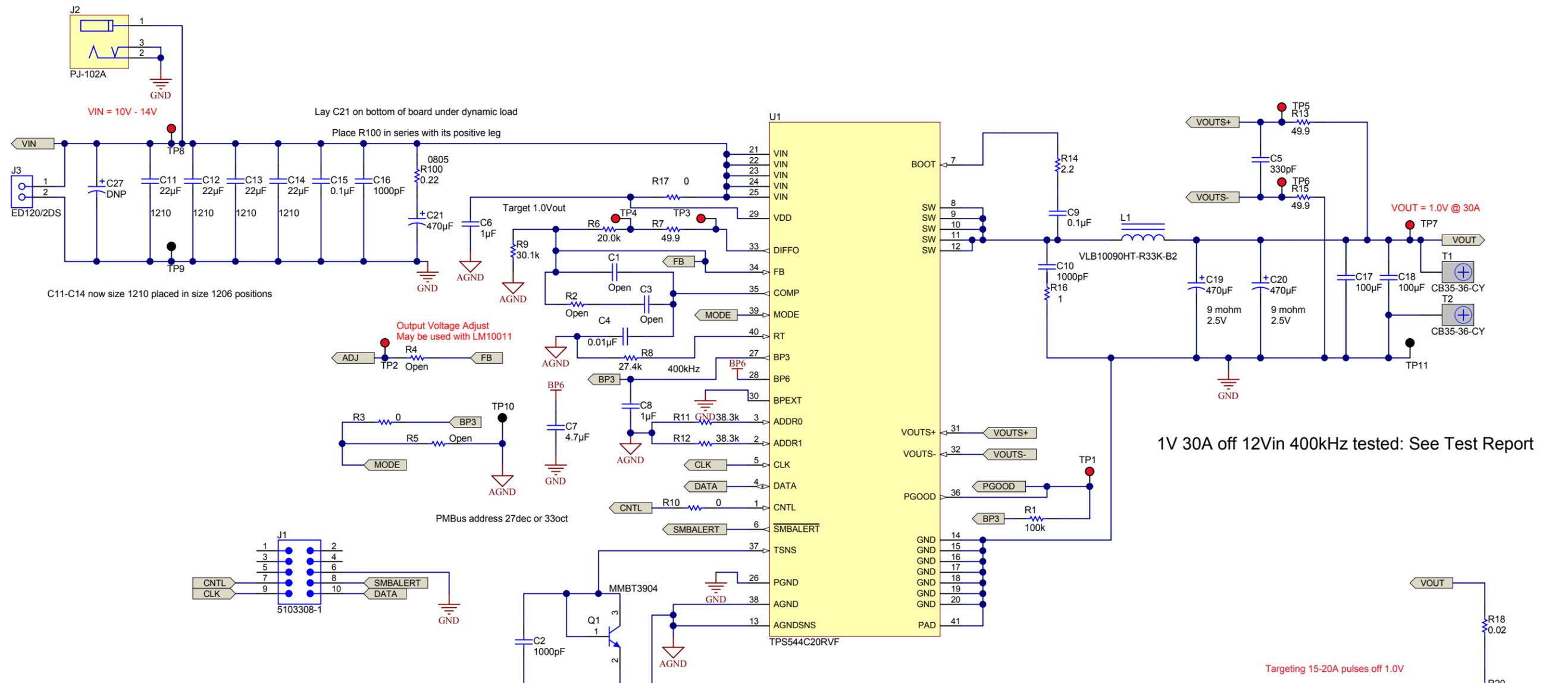
Designator
Hardware PMP10364.SchDoc



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Designed for: Public Release		Mod. Date: 10/27/2014	
Project Title: TPS544C20 EVM with Dynamic Load			
Number: PMP10364	Rev: A	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3	
Drawn By:	File: Cover PMP10364.SchDoc	Size: B	
Engineer: J Mandelcorn / C Sari	Contact: http://www.ti.com/support		





1V 30A off 12Vin 400kHz tested: See Test Report

Parts that change with different Vout:

R8: frequency setting: 10k for 250kHz, 17.8k for 300kHz, 27.4k for 400kHz, 38.3k for 500kHz, 56.2k for 650kHz, etc. See Table 1 page 18 datasheet

R9 for Vout setting: $R9 = (R6+R7) \cdot 0.6V / (Vout - 0.6V)$

0.6V is "VREF"; R6+R7 is now 20.05kohms

Main inductor value should go up for higher Vouts

However, only 0.33uH and 0.1uH are now available in needed "off the board" package as of Oct. 27, 2014

0.1uH would only be used for Vout < 1V and high load slew rate ~5A/usec

Output caps C19 & C20 as shown for 2V outputs and lower

For higher Vouts: use 220uF 6.3V 18mOhms such as 6TPE220MI POSCAP

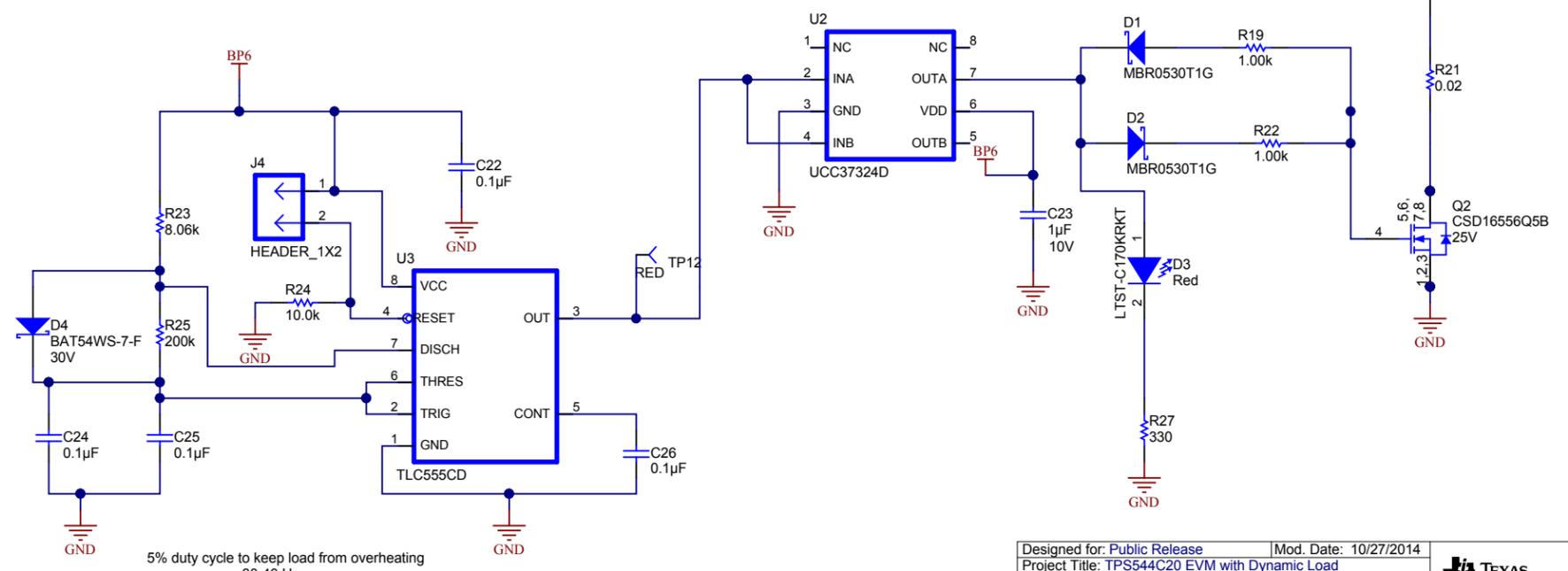
Those caps are on bottom side with max height of 2mm

Dynamic load resistors will change with Vout

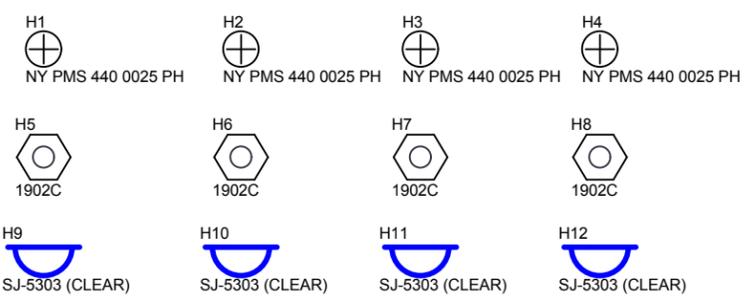
$R18 + R20 + R21 = [Vout / \text{desired step load}] \text{ minus } 5\text{mOhms}$

5% duty cycle to keep load from overheating 30-40 Hz

Targeting 15-20A pulses off 1.0V
Actual is 15A in 4 usec and 17A in all after 20usec



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PCB Number: PMP10364
 PCB Rev: A

LBL1
 PCB Label
 Size: 0.65" x 0.20"

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